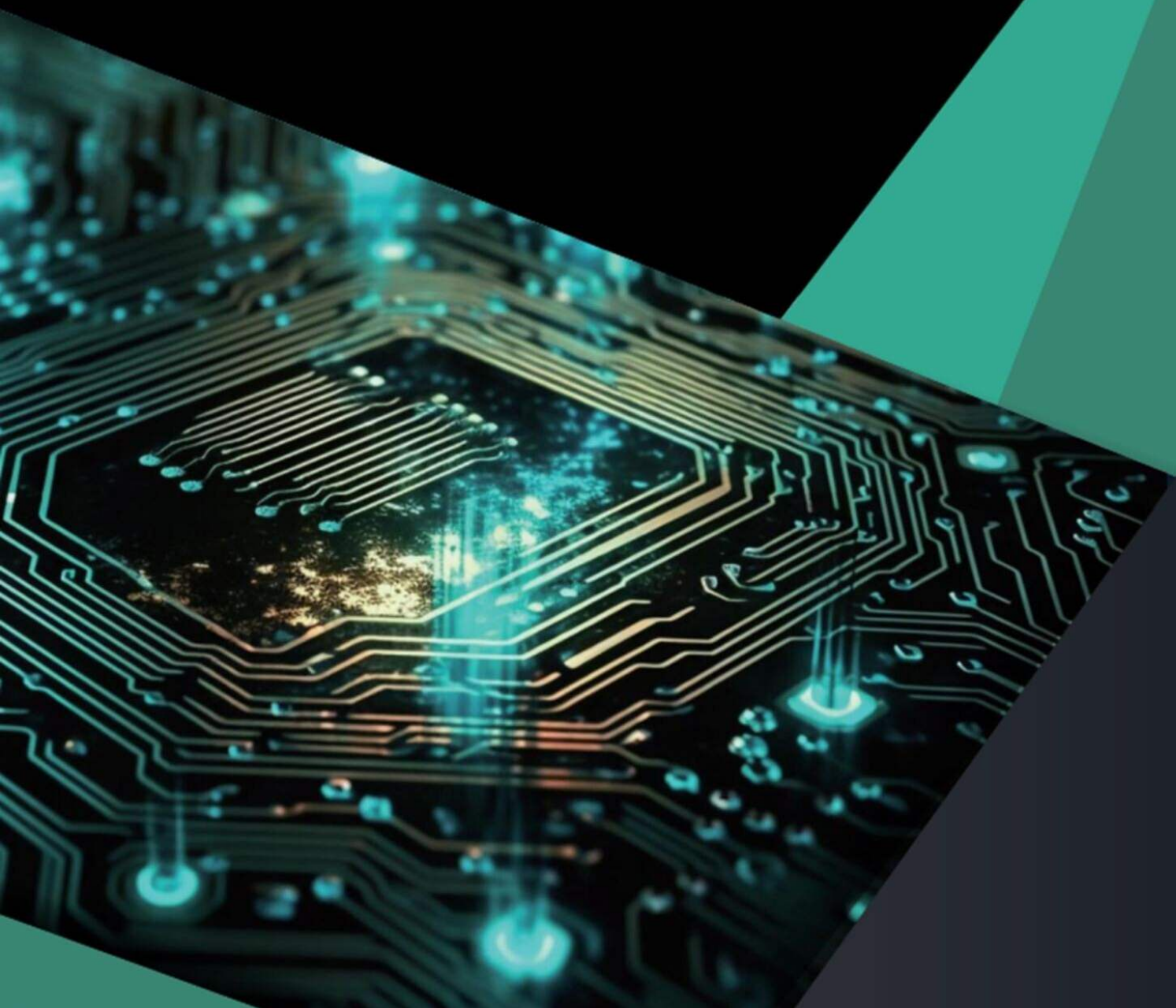
BRIOCEAN

October 2025

Monthly Market Updates

Your preferred supplier for global sourcing



About Briocean

Briocean was established in 2008 as ISO9001:2005, and ANSI/ESD S20.20-2021 certified leading independent electronic component distributor, with our headquarters in Singapore. Our company specialises in sourcing and supply chain management services for the electronic manufacturing clients across a broad range of industries.

Our global network of over 10,000 vetted suppliers allows us to respond to the unique needs of our clients, from reducing component shortages to achieving significant cost savings. Our robust supplier management system and two state-of-the-art quality assurance centres in Shenzhen and Hong Kong ensure that we deliver reliable, traceable procurement services.

At Briocean, quality is our cornerstone. Our commitment is to ensure that every component we source is of the highest quality.

Summary

Category	Trend
Macroeconomics	- United States/China: The two national leaders met in Busan to consult on tariffs, rare earths, Nvidia and related issues - Netherlands: The Dutch government imposes a national-security intervention on Nexperia, strengthening control over critical manufacturing stages - United Kingdom: Sanctions trigger strong Chinese response as tech-trade friction deepens - Japan: The Takaichi Cabinet launches a JPY 13 trillion stimulus package focused on semiconductors and AI - United States / Saudi Arabia: Advancing semiconductor dialogue and exploring cooperation opportunities - United States / Malaysia: Signing of reciprocal trade agreement places Malaysia's semiconductor supply chain under U.S. "appropriate consideration"
Industry (Short-term Impact)	- Nexperia: Supply Chain Disruptions Impact Global Automotive Industry, Multiple Automakers Face Production Halt Risks - NVIDIA: Market Capitalization Surpasses USD 5 Trillion Milestone, Reinforcing Leadership in AI Computing - Micron / Samsung / SK Hynix: Storage Chip Supply-Demand Imbalance Drives Price Increase Cycle - Samsung: Strong Storage Market Recovery Drives Notable Short-Term Growth - Micron: Strong Growth Driven by AI-Driven Storage Demand, with Both Earnings and Stock Price Seeing Significant Gains - NXP: Automotive Semiconductor Demand Shows Signs of Recovery, with Q3 Results Slightly Exceeding Market Expectations - Broadcom: Launches New "Thor Ultra" Networking Chip to Strengthen Its AI Data Center Portfolio - STMicroelectronics: Q3 2025 Earnings Reflect Persistent Weakness in Automotive Semiconductor Demand - SK Hynix: Q3 2025 Results Set Record as HBM Supply Lock-In Secures Short-Term Lead - GigaDevice: Short-Term Earnings Surge Amid Storage Industry Recovery

Category	Trend
Industry (Mid-term Impact)	- NVIDIA: Full-Stack AI Strategy Accelerated, Mid-Term Build-out of a Comprehensive Technology Ecosystem - Analog Devices (ADI): “Fab-Lite” Strategic Transition Optimises Mid-Term Capital Deployment - Infineon: SiC Packaging Collaboration to Enhance Mid-Term Supply-Chain Resilience - Microchip: Industry’s First 3 nm PCIe 6.0 Switch Addresses AI Data-Center Interconnect Bottlenecks - SK Hynix: Launch of “AIN Family” AI-Oriented Storage Solutions - Cmsemicon: Revenue Growth Amid Profit Pressure, Mid-Term Transformation Challenges
Industry (Long-term Impact)	- Silex: Silex Stake Sale Drives Short-Term Profit, Poses Long-Term Strategic Challenges - CXMT: Proposed 2026 STAR Market IPO, Strategic Valuation Significance - ASE: Major Investment in Advanced Packaging to Address Long-Term AI Chip Demand - Yageo: Acquisition of Shibaura Electronics Strengthens Long-Term High-End Component Portfolio - Skyworks & Qorvo: Strategic Merger to Reshape Long-Term RF Chip Market Dynamics
End-market (Artificial Intelligence)	- OpenAI and Broadcom Collaborate on Custom AI Chips - NVIDIA AI Chip Blackwell (GPU) Now Fully in Production in the U.S. - Qualcomm Unveils Two Data Center-Class AI Inference Chips - Intel Launches Next-Generation Data Center GPU
End-market (New Energy)	- CATL Advances Development of Sodium-Ion Passenger Vehicle Batteries - BYD Malaysia Plant Scheduled for 2026 Production
End-market (Consumer)	- Honor Launches Flagship Magic8 Series - vivo Unveils X300 Series Flagship Smartphones in Shanghai - Alibaba Cloud and NVIDIA Announce Physical AI Collaboration, Focusing on Embodied Intelligence and Assisted Driving
End-market (Industrial)	- Schneider Partners with Hongyu to Launch Okken Authorized Distribution Boards, Advancing Power Infrastructure Modernization - Rockwell Automation Launches Free FactoryTalk Design Workbench for Micro-Control Systems

Category	Trend
End-market (Automotive)	- Automakers Scramble for Chips Amid Nexperia Supply Constraints - NVIDIA Unveils Hyperion 10: Integrated Hardware-Software Platform for Autonomous Driving
End-market (Telecommunications)	- ZTE Secures Top Position in China's Cloud Terminal Market - NVIDIA Invests $1 Billion in Nokia to Advance AI-Driven 6G Networks
End-market (Medical Equipment & Devices)	- United Imaging Healthcare Signs INR 25 Billion Radiology Equipment Procurement Agreement with India's Super Health
Component Pricing & Product Insights	- Memory Chips: Spot NAND and DRAM Supplies Tighten Across the Board, Memory Prices Rise Firmly - GPU: AI Demand Drives High-End GPU Shortages and Further Price Increases - CPU: AI Becomes the Dominant Driver, Powering Demand Across the Entire Value Chain

Table Of Contents

01

Macro Environment Updates

1. Macro Environment

1.1 Industry Policy

1.1.1 United States/China: The two national leaders met in Busan to consult on tariffs, rare earths, Nvidia and related issues

On 30 October 2025, during the APEC Summit, the United States and China reached a trade framework agreement. Under the agreement, the U.S. will reduce its average tariff on Chinese goods from 57% to 47% and suspend the planned 100% additional tariffs scheduled for November; in turn, China has agreed to suspend rare-earth export controls for at least one year.

In the semiconductor sector: the U.S. side will permit Nvidia to engage in discussions on sales of certain AI-chip models to China, though the most advanced "Blackwell" architecture chips remain excluded from eligibility.

The agreement delivers three key benefits for the semiconductor industry: lower tariffs reduce trade-costs of chips; stabilized rare-earth supplies ensure security of critical materials; and the opening for dialogue on AI-chip sales injects positive expectations into technology trade. However, important details such as the specific Nvidia chip models, quantities, and licensing mechanisms remain unclear — thus, the actual improvement in supply-chains depends heavily on the subsequent implementation of those details. While the industry should seize this near-term easing opportunity, it must also remain vigilant about long-term geopolitical risks.

1.1.2 Netherlands: The Dutch government imposes a national-security intervention on Nexperia, strengthening control over critical manufacturing stages

On October 12, 2025, the Dutch government invoked the Goods Availability Act to intervene in Dutch semiconductor firm Nexperia, citing "serious governance deficiencies" that could endanger the security of key semiconductor technologies and manufacturing capabilities in the Netherlands and Europe.

This intervention led to a roughly 10% drop in the market value of Nexperia's parent company, Wingtech, on the Shanghai Stock Exchange. The Dutch government stressed that Nexperia may continue its operations, but it retains the authority to block any decisions deemed harmful. The incident underscores escalating competition over technological sovereignty within the semiconductor supply chain between Europe and the United States.

Following this, the Chinese government implemented export controls against Nexperia, prohibiting it and its subcontractors from exporting specific finished components and assemblies. This move has had a severe impact on Europe's automotive industry, with Volkswagen Group announcing the suspension of production of the Golf model at its Wolfsburg plant and a potential spill-over to other models.

Interim CEO Stefan Tilger of Nexperia warned clients strongly against receiving or using chips produced in Chinese plants on the grounds that they might not meet quality standards. In response, Nexperia's Chinese division issued a statement firmly opposing the Dutch side's allegations, emphasising that its products fully comply with technical standards and quality requirements, and pledging to safeguard supply-chain stability.

This episode not only exposes the fragility of global semiconductor supply chains but also highlights the complex interplay between national security, technological sovereignty and global supply-chain dynamics. In the context of escalating global tech competition and geopolitical risk, the semiconductor industry has become a key battleground at the intersection of industrial policy and trade policy.

1.1.3 United Kingdom: Sanctions trigger strong Chinese response as tech-trade friction deepens

On October 15, 2025, the Foreign, Commonwealth & Development Office (FCDO) updated the UK Sanctions List, placing 11 Chinese technology entities—including Yizhun Technology, Hongxin Micro Technologies (Hong Kong) and Ichi-Xin Electronics Technology—under asset-freeze and trust-service restrictions. The UK alleges these companies supplied critical items to Russia's energy and military sectors.

In response, on the evening of October 27, the Ministry of Commerce of the People's Republic of China issued a spokesman's Q&A via its official website, expressing a stern stance. China asserted the UK's action lacks basis in international law or United Nations authorisation, calling it a unilateral sanctions measure. The spokesman emphasised that the Chinese government consistently regulates exports of dual-use items in accordance with law, and that normal trade and cooperation between Chinese and Russian enterprises should not be interfered with or politicised.

The Ministry of Commerce further indicated that the UK's move—despite China's repeated representations and the positive trajectory of Sino-UK economic and trade relations—will inevitably have a negative impact on bilateral economic and trade cooperation. China urged the UK to immediately correct its misconduct, revoke sanctions on the relevant Chinese entities, and pledged to resolutely safeguard the legitimate rights and interests of Chinese enterprises.

Analysts note this sanctions incident marks a further deepening of China-UK policy friction in technology and export-control domains. Given the globalised nature of the semiconductor supply chain, such measures may in the short term increase supply-chain uncertainty, disrupt the international business activities of small- and mid-sized electronic-component distributors, and introduce new pressure into the regional tech-trade environment.

1.1.4 Japan: The Takaichi Cabinet launches a JPY 13 trillion stimulus package focused on semiconductors and AI

On 21 October 2025, Sanae Takaichi formally became Japan's Prime Minister and immediately proposed an economic-stimulus plan exceeding JPY 13 trillion (approx. USD 9.2 billion), designating artificial intelligence and semiconductors among its three strategic core pillars. The government also reorganised its economic policy architecture, abolishing the "Council for Realising New Capitalism" and establishing the "Japan Growth Strategy Council," signalling a shift in policy from "balanced growth and distribution" to "crisis-management investment + industrial strengthening."

At the international level, on 26 October Japan and ASEAN countries (including Vietnam) jointly held the "Vietnam–Japan Semiconductor Seminar," which aims to deepen regional semiconductor cooperation and build supply-chain resilience. These policies indicate that Japan is accelerating the positioning of the semiconductor industry at the heart of its national economic-security strategy: in the short term steering large-scale corporate investment into domestic or strategically aligned regions; in the long term driving the Japanese semiconductor supply chain from passive participation to strategic leadership and enhancing its voice within the global value chain.

1.1.5 United States / Saudi Arabia: Advancing semiconductor dialogue and exploring cooperation opportunities

In October 2025, the CEO of Intel Corporation, Lip-Bu Tan, met with Saudi Arabia's Minister of Communications & Information Technology, Abdullah Al-Swaha, to explore potential cooperation in semiconductors and artificial intelligence. This discussion aligns with Saudi Arabia's "Vision 2030" strategy of economic diversification and advanced technology development. Meanwhile, the U.S. and Saudi governments made progress on a semiconductor export agreement that would allow U.S. chip manufacturers to export high-performance chips for AI data centres to Saudi Arabia. These developments reflect a diversification trend in global semiconductor industry cooperation, with Middle Eastern capital increasingly integrating into the global technology supply chain.

1.1.6 United States / Malaysia: Signing of reciprocal trade agreement places Malaysia's semiconductor supply chain under U.S. "appropriate consideration"

On 26 October 2025, during the 47th ASEAN Summit in Kuala Lumpur, the United States—represented by Donald Trump—and Malaysia formally signed a milestone Reciprocal Trade Agreement. Key elements include: the U.S. granting zero-tariff treatment to approximately 1,711 Malaysian export items (including palm oil, rubber, cocoa, aerospace components, pharmaceuticals) valued at about USD 5.2 billion annually, representing roughly 12 % of Malaysia's exports to the U.S. In return, Malaysia committed to providing significant market access for U.S. industrial goods (such as chemicals, machinery, metals, passenger vehicles) and agricultural products (such as dairy, poultry, rice).

Although semiconductor products were not directly included in the zero-tariff list, the agreement explicitly states that when the U.S. makes tariff decisions under Section 232 of the Trade Expansion Act of 1962 for semiconductor products, Malaysia's commitments under this agreement will be taken into "appropriate consideration". This move provides additional assurance for Malaysia's role as a global hub in semiconductor packaging and testing, and strengthens its strategic position as a "trusted supply-chain base". In the short term, the agreement aids in reducing export barriers and boosting investment confidence; in the long term, it may drive deeper and broader development of Malaysia's semiconductor supply chain in the Indo-Pacific region, and offers substantive support for the U.S. "friend-shoring" supply-chain strategy.

1.2 Economic Indicators

1.2.1 September Global Manufacturing PMI Edges Down to 50.8; Regional Recovery Shows Significant Divergence

In September 2025, the global Manufacturing Purchasing Managers' Index (PMI), compiled by JPMorgan Chase & Co. and S&P Global, recorded 50.8, a slight decline of 0.1 points from August's 50.9. Despite the small dip, the index has remained above the neutral 50-mark for two consecutive months, marking the best sustained performance since June 2024 and signaling a steady post-pandemic recovery in global manufacturing.

Looking at regional performance, recovery trends were noticeably uneven:

Asia's major economies showed broad improvements: China's PMI rose to 51.2, returning to expansion territory for the first time since March; Japan's PMI hit 51.1, ending a 14-month contraction streak; South Korea's PMI came in at 50.7, indicating mild expansion.

North America remained strong: The U.S. PMI increased to 52.0, a 16-month high, with both new orders and production indicators improving.

Emerging markets stayed robust: India's PMI, while easing from 59.3 to 57.7, still maintained strong expansion momentum.

Europe underperformed: The Eurozone PMI fell to 49.8, slipping back into contraction, showing that the region's manufacturing recovery lacks momentum.

While global manufacturing output posted its third growth in four months and new orders showed moderate gains, the overall recovery remains fragile. Notably, global manufacturing employment saw a slight decline in September, and uncompleted orders have fallen for the 39th consecutive month, reflecting that excess capacity in the sector remains unresolved and demand-side support is still unstable.

This regional disparity in recovery is directly influencing semiconductor demand: Continued growth in North America and parts of Asia is expected to drive demand for consumer electronics and automotive chips, while weakness in Europe may slow the recovery in industrial semiconductor demand. Businesses need to stay alert to regional PMI movements and adjust their strategies to better align with demand shifts across different markets.

Global Manufacturing by Region PMI

Period	Global	China	Japan	Korea	India	Americas	Eurozone
2023-11	49.30	49.40	48.30	50.00	56.00	46.70	44.20
2023-12	49.00	49.00	47.90	49.90	54.90	47.40	44.40
2024-01	50.00	49.20	48.00	51.20	56.50	49.10	46.60
2024-02	50.30	49.10	47.20	50.70	56.90	47.80	46.50
2024-03	50.60	50.80	48.20	49.80	59.10	50.30	46.10
2024-04	50.30	50.40	49.60	49.40	58.80	49.20	45.70
2024-05	50.90	49.50	50.40	51.60	57.50	48.70	47.30
2024-06	49.50	49.50	50.00	52.00	58.30	51.70	45.60
2024-07	49.80	49.40	49.10	51.40	58.10	46.80	45.80
2024-08	48.90	49.10	49.80	51.90	57.50	47.20	45.60
2024-09	48.80	49.80	49.70	48.30	56.50	47.20	45.00
2024-10	48.80	50.10	49.80	48.30	57.50	46.50	46.00
2024-11	50.00	50.30	49.00	50.60	56.50	48.40	45.20
2024-12	49.60	50.10	49.60	49.00	56.40	49.20	45.10
2025-1	50.10	49.10	48.70	50.30	57.70	50.90	46.60
2025-2	50.60	50.20	49.00	49.90	56.30	50.30	47.60
2025-3	50.30	50.50	48.40	49.10	58.10	49.00	48.60
2025-4	49.80	49.00	48.70	47.50	58.20	48.70	49.00
2025-5	49.60	49.50	49.40	47.70	57.60	48.50	49.50
2025-6	50.30	49.70	50.10	48.70	58.40	49.00	50.50
2025-7	49.70	49.30	49.90	48.00	59.20	48.00	49.80
2025-8	50.90	50.50	52.00	48.30	59.30	53.00	50.70
2025-9	50.80	51.20	51.10	50.70	57.70	52.00	49.80

Source：Wind

1.2.2 Global Semiconductor Sales Rise by 21.7% in August 2025, Strong Growth in APAC and Americas

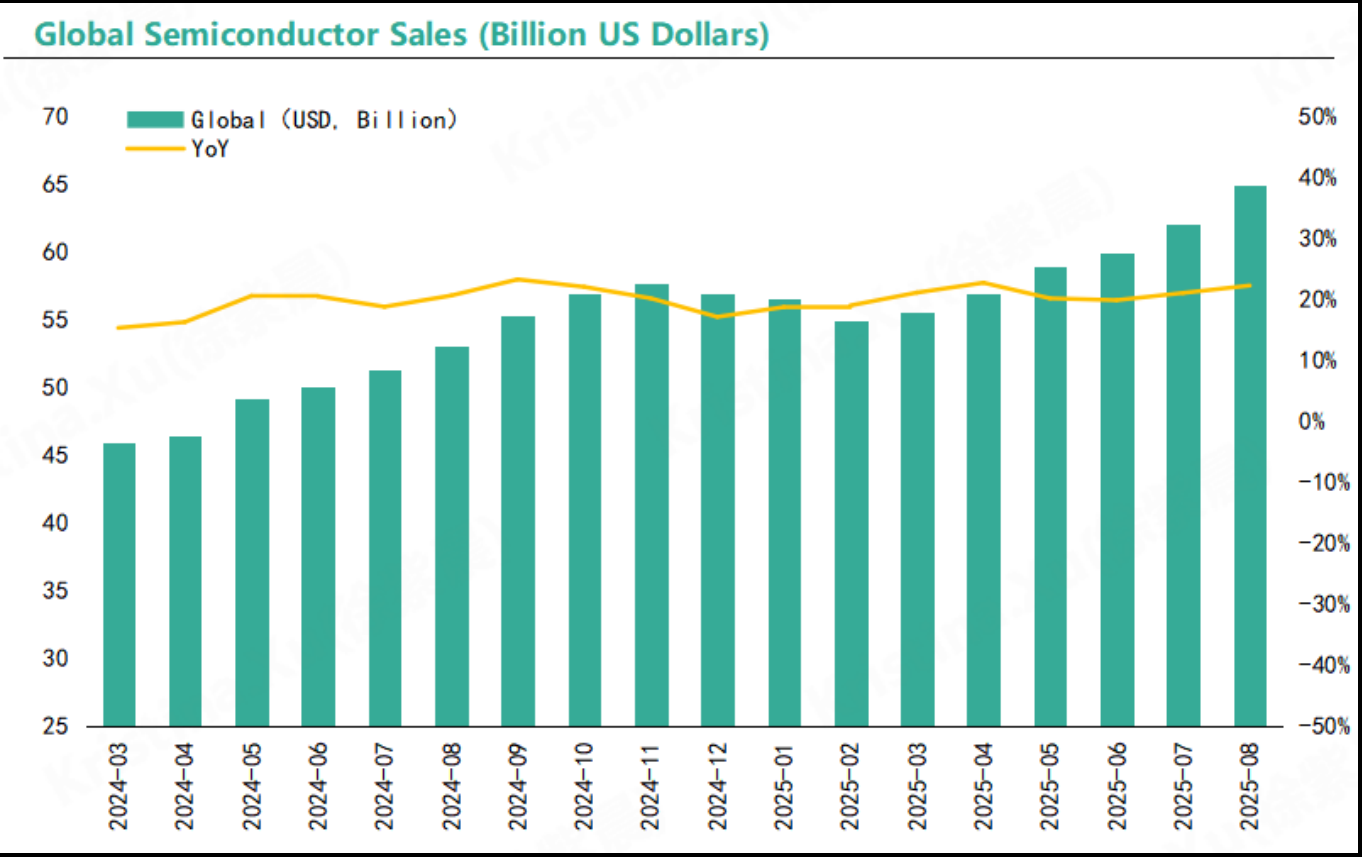
In August 2025, global semiconductor sales totaled USD 64.9 billion, marking a 21.7% year-over-year increase from USD 53.3 billion in August 2024, along with a 4.4% month-over-month increase compared to USD 62.1 billion in July 2025. According to the World Semiconductor Trade Statistics (WSTS), this growth was primarily driven by robust demand in the Asia-Pacific and Americas regions, with particularly strong sales in memory and logic chips.

Regionally, the Asia-Pacific and other regions led with a 43.1% year-over-year increase in sales. The Americas market grew by 25.5%, showing solid performance. China's market expanded by 12.4%, indicating potential for further growth despite a more moderate increase. The European market saw a 4.4% year-over-year growth, indicating slower progress, while Japan's market contracted by 6.9%, reflecting weaker semiconductor demand in the region.

In terms of month-over-month performance, the Asia-Pacific and other regions experienced a 6.9% increase, while the Americas grew by 4.3% and China by 3.3%. Japan and Europe showed more modest month-over-month growth at 2.0% and 1.0%, respectively. These figures highlight the variation in regional performance, but the overall trend in global semiconductor sales remains positive.

John Neuffer, President and CEO of the Semiconductor Industry Association (SIA), commented, "Global semiconductor sales in August continued to grow well above last year's levels, with Asia-Pacific and Americas markets leading the charge. Memory and logic chip sales were key drivers of this growth."

Overall, the August 2025 semiconductor sales data demonstrates that global demand, particularly in the Asia-Pacific and Americas regions, remains strong, propelling overall market growth. Despite weaker performance in Japan, the continued expansion of sectors such as AI, data centers, and high-performance computing is expected to support growth in the global semiconductor market through the second half of the year. Regional disparities, especially in the context of growing trade policy and geopolitical uncertainties, should be closely monitored.



Source：SIA

1.2.3 US 10-Year Treasury Yield: Volatile Downtrend in October, Dropping Below 4.0% Mid-Month

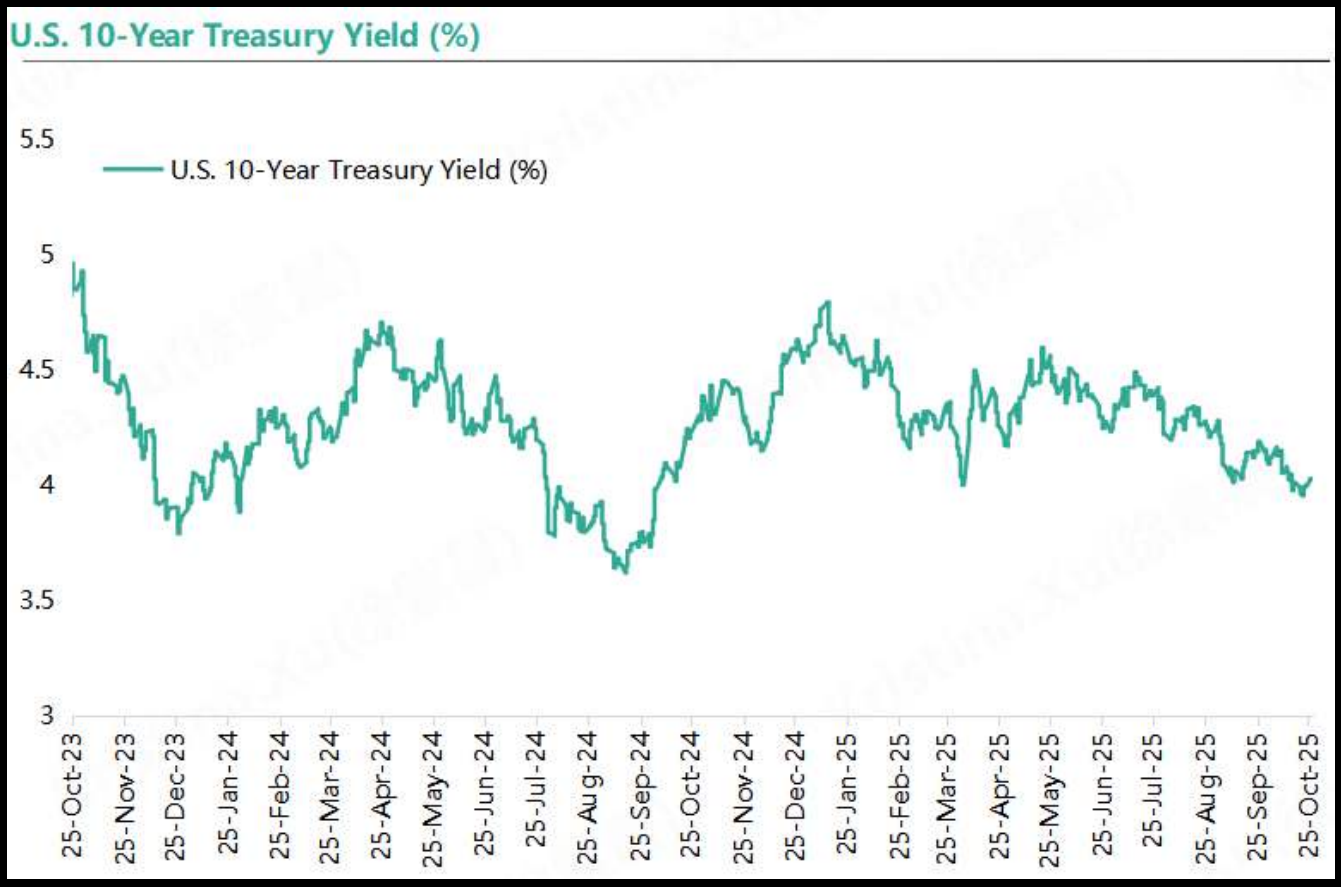
In October 2025, the US 10-year Treasury yield exhibited a downward fluctuation, gradually retreating from the 4.10% level at the beginning of the month. After reaching 4.119% on October 3, the yield entered a downward trajectory, hitting a monthly low of 3.976% on October 16, falling below the 4.0% psychological threshold for the first time since July. Despite a slight rebound to 4.022% (on October 27) driven by optimism surrounding US-China trade negotiations, the yield still ended the month with a cumulative drop of around 12 basis points, reflecting market concerns about the economic outlook and growing expectations of monetary policy easing.

Factors influencing interest rate movements in October were a mix of bullish and bearish pressures: On one hand, weak economic data emerged, with September non-farm payrolls adding only 128,000 jobs and the unemployment rate rising to 4.4%, along with a 0.8% month-over-month decline in retail sales and a dip in consumer confidence, suggesting a slowdown in economic growth. On the other hand, inflationary pressures showed signs of easing, with the September CPI rising by 2.6% year-over-year and core CPI dropping to 2.8%, marking three consecutive months of decline and the lowest since March 2024, thus creating room for the Federal Reserve to implement easing policies.

Against this backdrop, expectations for Fed policy shifted notably, with the futures market indicating a high probability that traders anticipated a 25 basis point rate cut at the October meeting and forecasted multiple rate cuts by early 2026. Notably, by late October, optimism over a potential US-China trade deal partially offset the rate cut expectations, causing the Treasury yield to rise slightly towards the end of the month.

Regarding the long-term yield outlook, there was a significant divergence in market analysis. A Reuters survey of economists projected that the 10-year yield would fluctuate around 4.1% over the next three months, while some economists warned that yields could rise to 6% or higher in the next one to two years if inflation picks up again.

Overall, the downward fluctuation of the US 10-year Treasury yield in October accurately reflected the market's strong expectation for a shift toward a more accommodative monetary policy, given weaker economic data and slowing inflation. The future trajectory of yields will primarily depend on the extent of the economic slowdown, the persistence of inflationary relief, and the final outcome of US-China trade negotiations. Investors should closely watch the FOMC statement and the Summary of Economic Projections (SEP) from the early November meeting for updated guidance on the interest rate path.



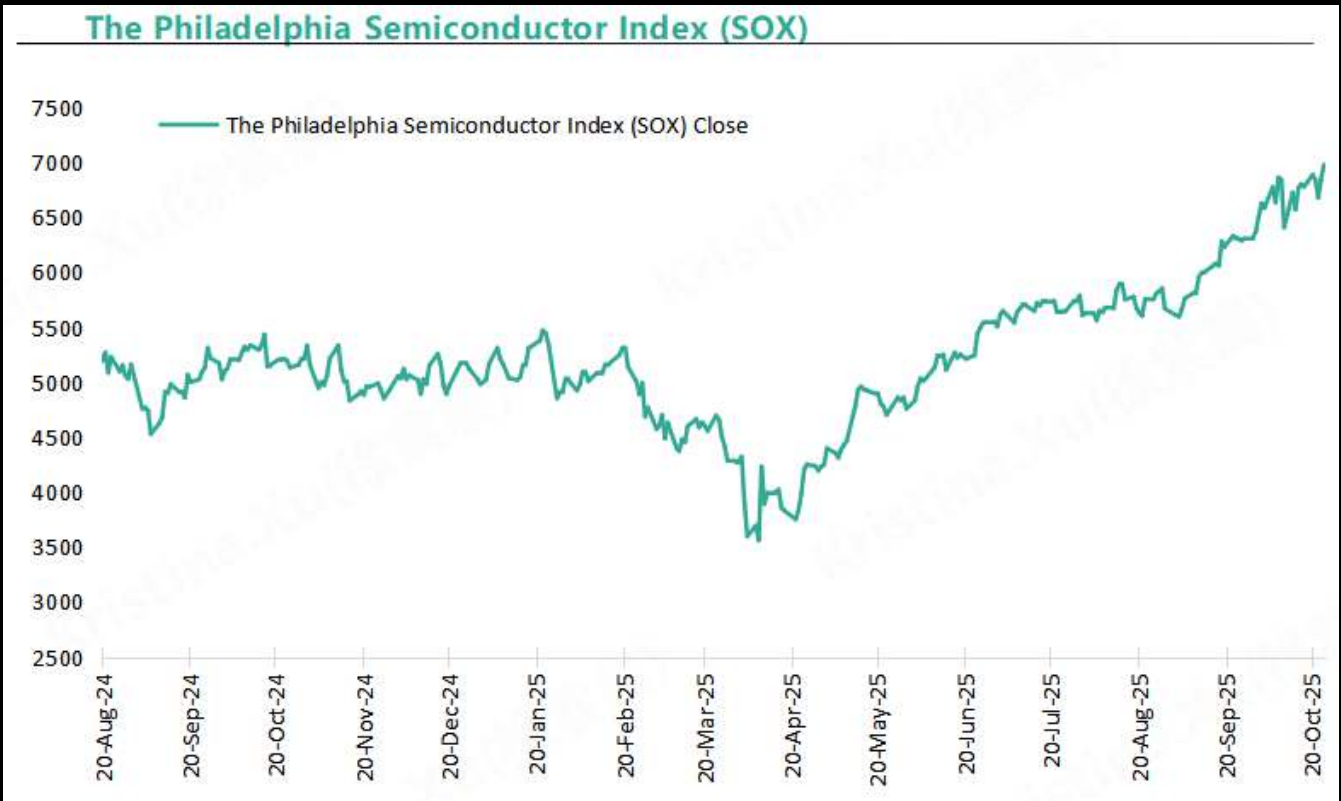
Source：Investing

1.2.4 Philadelphia Semiconductor Index Trend in September-October: Policy Support and Earnings Recovery Drive Index Above 6900

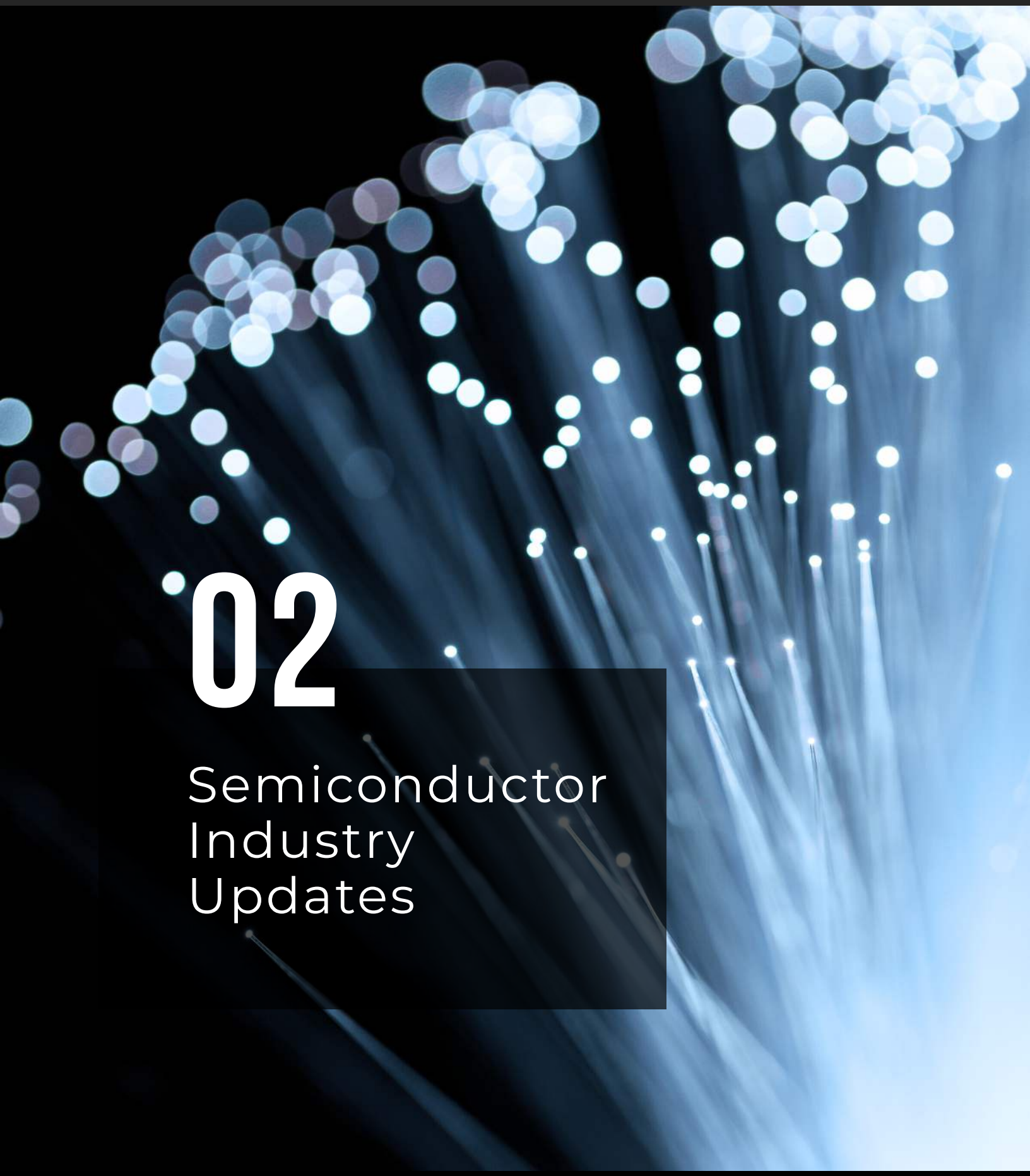
In September and October 2025, the Philadelphia Semiconductor Index demonstrated a solid upward trend, rising from around 6300 points in late September to a record high of 6976.90 points on October 24, marking a cumulative gain of over 10.8%, significantly outperforming the broader market. This rally was primarily driven by multiple favorable factors. After breaking through the key resistance level of 6500 points in early October, the index continued to strengthen, reaching a peak of 6860.20 points on October 8. This surge was fueled by the US Department of Commerce's official implementation of the US-Malaysia semiconductor cooperation agreement, which granted equipment export tariff exemptions, better-than-expected Q3 earnings from major chipmakers, and rising expectations for the Federal Reserve to maintain accommodative monetary policies.

With support from both the policy environment and improving fundamentals, the semiconductor sector displayed strong upward momentum. On one hand, the US government's continued support for the semiconductor industry and the relatively loose monetary environment created favorable conditions for sector performance. On the other hand, industry fundamentals showed positive changes, with global semiconductor sales continuing to rise, supply chain inventories further optimizing, and demand in emerging sectors such as artificial intelligence (AI) and automotive electronics maintaining strong growth. Despite a brief technical pullback to 6407.60 points on October 10, the index quickly regained momentum following better-than-expected earnings reports and a positive industry outlook, with several consecutive trading days of gains after October 13, demonstrating strong market resilience.

Overall, the robust performance of the Philadelphia Semiconductor Index in September and October reflects the recovery of the global semiconductor industry driven by policy support, earnings recovery, and technological innovation. With continued demand from sectors such as AI, automotive electronics, and industrial digitization, the semiconductor sector is expected to remain relatively strong in Q4, and investors should focus on leading companies with core competitive advantages in segments such as AI computing power and automotive semiconductors.



Source : MacroMicro



02

Semiconductor Industry Updates

Semiconductor Industry Overview

Impact	Manufacturer	Updates	Analysis
Short-term	Nexperia	Global trade shifts have disrupted automotive-grade chip supply, pressuring Nissan and Honda and risking assembly line stoppages	Supply Chain Disruption Sparks Industry Crisis: As a key supplier with a 40% market share in basic chips, its supply fluctuations are directly affecting the automotive sector, highlighting global supply chain vulnerabilities.
	NVIDIA	Its stock opened up 3.2% in October, lifting market cap past USD 5 trillion—the first public company to ever reach this milestone	Historic Market Cap: Extreme optimism around AI computing power demand drove its valuation to unprecedented levels, boosting sentiment across the entire semiconductor sector.
	Micron/Samsung/ SK Hynix	Samsung will hike Q4 DRAM/NAND prices, Micron has paused quoting, and SK hynix has begun mass production of 321-layer QLC NAND	Memory Chips Enter Price Hike Cycle: Factory production cuts and a shift toward HBM and DDR5 have led to tight supply in traditional DRAM and NAND, causing prices to rise across the board in the short term.
	Samsung	Q3 revenue hit KRW 86.1 trillion with record memory sales and operating profit of KRW 12.2 trillion	Memory Market Recovery Drives Earnings Growth: Strong demand for HBM3E and server SSDs boosted semiconductor profits, signaling the memory cycle has entered an uptrend.
	Micron	Q4 FY2025 revenue rose 46% YoY to USD 11.315 billion, with the stock up 22.7% post-earnings and sampling of the 192GB SOCAMM2 module underway	Strong Earnings Growth Exceeds Expectations: This demonstrates its leadership in the AI data center storage market, with new products likely to further solidify its advantage.

Semiconductor Industry Overview

Impact	Manufacturer	Updates	Analysis
Short-term	NXP	Q3 revenue reached USD 3.17 billion, beating expectations with automotive chips up 6% QoQ, and Q4 guidance set above market forecasts	Signs of Recovery in the Automotive Semiconductor Market: The company's improved performance has boosted market confidence in the short-term demand for automotive electronics.
	Broadcom	Launched new network chip Thor Ultra to strengthen AI data center presence	Broadcom advances in the data center infrastructure market by introducing AI interconnect chips.
	STMicroelectronics	Q3 revenue was USD 3.19 billion, down 2% YoY, with Q4 guidance slightly below expectations and 2025 capex trimmed to ~USD 2 billion	Slowing EV Demand Weakens Automotive Power Device Business: However, image sensors and MCUs performed steadily, with short-term performance supported by consumer electronics and industrial markets.
	SK hynix	Q3 revenue hit KRW 24.45 trillion with record operating profit of KRW 11.38 trillion and net profit up 119% YoY. HBM supply talks for 2026 are completed, with HBM4 shipments expected in Q4	Record Performance and Supply Lock-In: The surge in demand for HBM3E and server DDR5 drove profits to a new high, with customer supply agreements completed early to ensure short-term business visibility.
	GigaDevice	Q3 revenue reached CNY 2.681 billion, up 31.4% YoY; net profit was CNY 508 million, up 61.13% YoY	Benefiting from Recovery in the Storage Industry: The improvement in DRAM supply dynamics has led to a "price and volume increase" trend, significantly boosting short-term performance.ew products likely to further solidify its advantage.

Impact	Manufacturer	Updates	Analysis
Mid-term	NVIDIA	Announced collaboration with Nokia on AI-native 6G, NVQLink quantum tech, and €1B investment with Deutsche Telekom in European AI data centers	Building a Full-Stack AI Ecosystem: Expanding technological boundaries and deepening global market penetration through 6G, quantum computing, and regional computing power deployments.
	ADI	Signed MoU with ASE to sell its Penang testing/assembly facility and adopt a "Fab-Lite" model	"Fab-Lite" Becomes Industry Trend: By divesting heavy assets, the company aims to optimize capital efficiency and focus on core technologies to meet changing market demands.
	Infineon	Signed MoU with ROHM to share tech and serve as secondary suppliers for certain SiC power device packaging	Enhancing Supply Chain Resilience: By standardizing packaging and building a second-supplier system, the partnership improves procurement flexibility to mitigate geopolitical risks.
	Microchip	Launched the first PCIe Gen 6 switch on 3nm, supporting 160 channels and post-quantum encryption	Breaking the AI Compute Bottleneck: The new product enhances interconnect efficiency within data centers, laying the groundwork for medium-term expansion of AI clusters.
	SK hynix	Introduced "AIN Family" AI-NAND at OCP 2025 for AI storage	AI Training/Inference High-Bandwidth NAND Product Strategy: The strategy for high-bandwidth NAND products for AI training/inference is taking shape, with expectations to enhance market position in the medium term.
	Cmsemicon	Q3 revenue CNY 269M (+21.88% YoY); net profit CNY 65.82M (-3.66% YoY)	Growth and Challenges During Business Transformation: Revenue growth indicates market recovery, but profit decline reflects mid-term pressure from product structure adjustments and increased R&D investment.

Impact	Manufacturer	Updates	Analysis
Long-term	Silex	Q3 net profit surged 2199% from Silex sale; adjusted net loss widened to -CNY 235M	Strategic Transformation Growing Pains: The sale of a core subsidiary generated substantial short-term gains, but long-term challenges remain due to weakened MEMS process capabilities and concerns over the sustainability of the main business.
	CXMT	Plans STAR Market IPO in early 2026, valuation up to CNY 300B	Capitalization of DRAM/Storage Route: This marks a significant milestone for the capitalization of the DRAM/storage route, with strategic importance for long-term domestic substitution.
	ASE	Investing in Kaohsiung K18B advanced packaging plant, completion by 2028 for AI/HPC demand	Expanding Advanced Packaging Capacity: Responding to the long-term packaging demand for AI chips, solidifying its core position in backend processes.
	Yageo	Plans full acquisition of Shibaura Electronics for TWD 22.8B, closing by Q1 2026	Expanding Sensor Business Through M&A: Strengthening the product portfolio and global market presence in the long term through this acquisition.
	Skyworks/Qorvo	Announced USD 22B merger, creating a leader in RF, analog, and mixed-signal semiconductors by early 2027	Reshaping the RF Chip Competitive Landscape: The merger will create a new RF chip giant, enhancing long-term competitiveness in mobile, defense, automotive, and other markets through integrated complementary technologies.

2. Semiconductor Industry Updates

2.1 Short-term Implications

2.1.1 Nexperia: Supply Chain Disruptions Impact Global Automotive Industry, Multiple Automakers Face Production Halt Risks

In October 2025, shifts in the international trade environment surrounding Nexperia had a direct and significant impact on the global automotive sector. Regulatory actions by the Dutch government and export restrictions imposed by China's Ministry of Commerce have disrupted the stable supply of automotive-grade base chips produced by Nexperia. As a result, supply chain strains have emerged: Nissan publicly stated that its chip inventory would be depleted by the first week of November, while Honda has suspended production at its Mexico facility and adjusted output at its U.S. and Canadian plants. The European Automobile Manufacturers Association (ACEA) has also warned that some member companies may face production stoppages in the coming days.

Market analysis reveals that Nexperia holds approximately 40% of the market share in base chips, which are critical components in key automotive modules. Although automakers are exploring alternative sources, the certification process for automotive-grade chips can take several months, presenting challenges for short-term substitution. The CEO of Mercedes-Benz noted that the resolution of this crisis will require negotiations. This incident highlights the inherent vulnerability of global supply chains in the context of evolving trade dynamics, making it a pressing issue for the semiconductor industry in the near term.

2.1.2 NVIDIA: Market Capitalization Surpasses USD 5 Trillion Milestone, Reinforcing Leadership in AI Computing

NVIDIA's stock price surged by 3.2% at the beginning of October 2025, propelling its market capitalization beyond the USD 5 trillion threshold, making it the first publicly traded company to achieve this landmark. This market performance significantly exceeds the total market capitalization of major European economies, such as the UK and France, reflecting an exceptionally optimistic outlook from capital markets regarding the growing demand for AI computing capabilities. This development is expected to further enhance investor sentiment across the broader semiconductor sector.

In the medium term, this remarkable surge in market value strengthens NVIDIA's capital position, providing greater capacity for expansion through equity financing and mergers and acquisitions, particularly in emerging areas such as 6G and quantum computing. Long-term, the USD 5 trillion market valuation not only underscores NVIDIA's dominant position in the AI training and inference markets but also signals its successful transition from a chip manufacturer to a full-stack AI infrastructure provider, creating formidable barriers to entry for competitors and solidifying its leadership in the AI ecosystem.

2.1.3 Micron / Samsung / SK Hynix: Storage Chip Supply-Demand Imbalance Drives Price Increase Cycle

According to TrendForce, Samsung Electronics has announced price hikes for Q4, with DRAM prices increasing by 15% to 30% and NAND flash prices rising by 5% to 10%. Meanwhile, Micron has paused its pricing due to strategic decisions regarding pricing and capacity allocation. These developments indicate that the storage market has entered a full-scale price increase cycle, which will positively impact the revenue and profit margins of key storage manufacturers in the short term.

The underlying cause of this price surge is a structural supply-demand imbalance: on one hand, AI inference applications are driving robust demand for high-capacity enterprise SSDs; on the other hand, Samsung, Micron, and SK Hynix are shifting production capacity toward higher-margin products such as HBM and DDR5, while scaling back or halting production of legacy products like DDR4, resulting in tighter supply.

Looking ahead, the long-term growth engine for these manufacturers is the increasing demand from AI servers and data centers for high-performance storage solutions. According to Yole Group, the HBM market is projected to maintain a 33% compound annual growth rate (CAGR) through 2030, which will continue to reshape storage manufacturers' long-term product strategies and investment priorities.

2.1.4 Samsung: Strong Storage Market Recovery Drives Notable Short-Term Growth

Samsung's Q3 2025 financial results show consolidated revenue of KRW 86.1 trillion, up 15.4% quarter-over-quarter, and operating profit of KRW 12.2 trillion, reflecting a 32% year-on-year increase. This robust performance was primarily driven by the strong showing of its Device Solutions (DS) division, with memory sales hitting a historic high. The main drivers of this growth were strong demand for HBM3E high-end products and server solid-state drives (SSDs), reflecting sustained demand for high-performance storage solutions in the AI server market.

In the medium term, the full recovery of the storage market will allow Samsung to further refine its product portfolio, boost profitability, and strengthen its competitive position vis-à-vis Micron and SK Hynix. In the long term, Samsung's leadership in HBM technology and its growing footprint in the AI data center market will provide a solid foundation for the company to maintain a competitive edge as the digital economy evolves.

2.1.5 Micron: Strong Growth Driven by AI-Driven Storage Demand, with Both Earnings and Stock Price Seeing Significant Gains

For the fiscal fourth quarter ending August 28, 2025, Micron posted a record revenue of USD 11.315 billion, marking a 46% year-on-year increase. This robust growth was primarily fueled by the surging demand for high-performance storage solutions, particularly HBM, within AI data centers. The company also saw a significant improvement in gross margins, and its stock price surged 22.7% within a month of the earnings report, significantly outperforming the broader market. This performance has notably enhanced market confidence in the storage sector.

Simultaneously, Micron announced the commencement of customer sampling for its new 192GB SOCAMM2 memory modules, offering a 50% increase in capacity and a 20% improvement in energy efficiency while maintaining the same form factor.

In the medium term, the introduction of such high-capacity, low-power products is critical for consolidating Micron's leadership in the AI data center market, catering to the growing demand for evolving AI infrastructure. Long-term, Micron's dominance in advanced memory technologies such as HBM, alongside its USD 7.2 billion stock repurchase program, underscores the management's strong confidence in the company's sustained cash flow and business fundamentals, providing a solid foundation for continued investment and competitiveness in the fast-evolving technology space.

2.1.6 NXP: Automotive Semiconductor Demand Shows Signs of Recovery, with Q3 Results Slightly Exceeding Market Expectations

In October 2025, NXP Semiconductors reported Q3 2025 revenue of USD 3.17 billion, a 2.4% decline year-on-year, but slightly surpassing the market consensus of USD 3.16 billion. Short-term, the company's automotive segment saw a 6% quarter-on-quarter revenue growth, signaling a positive recovery in automotive semiconductor demand, which led to a notable increase in its stock price. The company's Q4 revenue guidance also exceeded market expectations, reinforcing the short-term optimistic sentiment.

In the medium term, NXP's recent acquisitions, including its purchase of automotive networking company Aviva Links, reflect its strategic focus on bolstering its presence in automotive intelligence and electrification, capitalizing on growth opportunities stemming from the industry recovery.

Long-term, the ongoing evolution of automotive electronics and the steady expansion of industrial IoT will provide clear demand support, strengthening NXP's long-term product development and positioning in the semiconductor market.

2.1.7 Broadcom: Launches New “Thor Ultra” Networking Chip to Strengthen Its AI Data-Center Portfolio

Broadcom announced in October 2025 the launch of its next-generation networking chip, Thor Ultra, designed for interconnect within AI data centers and communication across large-scale accelerator clusters. The new chip expands Broadcom’s role in AI infrastructure and intensifies competition with manufacturers such as NVIDIA Corporation. In the short term, the launch enhances Broadcom’s influence in the high-growth AI-accelerator and network-interconnect segment; in the medium term, it is expected to drive sizeable data-center customer orders and elevate the company’s position within the AI computing ecosystem. Over the long term, if Broadcom continues to advance synergy across interconnect, switching, and custom accelerators, it may emerge as a “hidden champion” behind next-generation AI system architectures.

2.1.8 STMicroelectronics: Q3 2025 Earnings Reflect Persistent Weakness in Automotive Semiconductor Demand

STMicroelectronics released its third-quarter 2025 financial results on October 23. The company reported net revenues of USD 3.19 billion, down 2.0% year over year; a gross margin of 33.2%, 460 basis points lower than the prior-year period; and net income of USD 237 million, representing a 32.3% year-over-year decline.

Despite projecting fourth-quarter revenues to rise 2.9% sequentially to USD 3.28 billion, with an estimated gross margin of 35.0%, overall performance continues to be weighed by soft demand in the automotive semiconductor segment. CEO Jean-Marc Chery noted that while personal electronics and microcontroller businesses performed solidly, both automotive and industrial divisions remain challenged. Consequently, the company has trimmed its 2025 capital-expenditure plan to just under USD 2 billion to adapt to current market conditions.

Overall, STMicroelectronics is benefiting in the near term from growth in personal electronics and MCU products, but the prolonged downturn in automotive semiconductors may continue to pressure financial performance. Close monitoring of the automotive market’s recovery will be essential to guide future strategic adjustments.

2.1.9 SK Hynix: Q3 2025 Results Set Record as HBM Supply Lock-In Secures Short-Term Lead

SK Hynix's Q3 2025 financial report revealed exceptional performance: revenue stood at KRW 24.45 trillion, operating profit reached KRW 11.38 trillion (a record high), and net profit surged 119% year-on-year to KRW 12.60 trillion, with an operating margin rising to 47%.

In the short term, these outstanding results were driven by explosive demand from AI servers for HBM3E and high-capacity DDR5 products—with shipments of DDR5 modules of 128 GB and above more than doubling from the previous quarter. In addition, the company announced it has completed customer supply negotiations for 2026 HBM and will begin shipments of next-generation HBM4 in Q4, ensuring strong capacity-utilisation and revenue visibility for coming quarters.

SK Hynix's cash and cash equivalents rose to KRW 27.9 trillion, achieving a net-cash position and providing robust financial flexibility for short-term capacity expansion and technology upgrades. These developments reflect how the company, through its early positioning in the AI-storage segment, has built a significant competitive advantage in the near term.

2.1.10 GigaDevice: Short-Term Earnings Surge Amid Storage Industry Recovery

In Q3 2025, GigaDevice reported revenue of CNY 2.681 billion, representing a year-on-year increase of 31.40%. Net profit attributable to shareholders reached CNY 508 million, up 61.13% compared with the same period last year.

The company's strong short-term performance was primarily driven by an improved DRAM supply environment, which enabled a favourable "price–volume up" trend. Looking at the medium term, the combination of storage-industry recovery and GigaDevice's strategically positioned niche DRAM and custom storage solutions offers a path to further market share gains. Long-term, its ongoing investment in storage-chip technology and alignment with the domestic substitution trend could establish a sustainable competitive advantage in the increasingly competitive memory market.

2.2 Mid-term Implications

2.2.1 NVIDIA: Full-Stack AI Strategy Accelerated, Mid-Term Build-out of a Comprehensive Technology Ecosystem

At the 2025 GTC conference in Washington, NVIDIA CEO Jensen Huang unveiled the company's full-stack AI strategy, highlighting three strategic domains: 6G communications, quantum computing, and regional compute infrastructure. In the medium term, NVIDIA announced collaboration with Nokia to develop an AI-native 6G network platform. It also introduced the NVQLink architecture, which integrates GPU-based supercomputing with quantum processors and is supported by 17 quantum computing firms. Meanwhile, NVIDIA partnered with Deutsche Telekom to invest EUR 1 billion in an AI data centre in Munich, deploying approximately 10,000 GPUs. These coordinated initiatives create substantial strategic synergy: the 6G deployment targets next-generation communication standards, quantum computing positions NVIDIA at the research frontier, and the European data centre directly addresses regional compute demand. In the short term, these announcements further solidified market confidence in NVIDIA's growth potential, contributing to its market capitalisation surpassing USD 5 trillion. Over the long term, NVIDIA is transitioning from a GPU-hardware supplier to a full-stack AI solutions provider spanning communications, compute, and infrastructure—this ecosystem strategy is poised to deliver sustained competitive advantage and growth momentum in the global digital economy.

2.2.2 Analog Devices (ADI): "Fab-Lite" Strategic Transition Optimises Mid-Term Capital Deployment

ADI signed a memorandum of understanding with ASE Technology Holding Co. to divest its assembly & test facility in Penang, Malaysia. This follows similar moves by other industry players and signals a broader shift toward a "Fab-Lite" model in analogue and power semiconductor leadership. In the mid-term, this shift is more than a simple "outsourcing" of manufacturing—it is a deliberate strategic choice. By shedding high-capital, lower-return backend packaging/testing assets, ADI expects to reduce capital-expenditure-to-revenue ratios (e.g., from ~10% to ~6%) and to redirect cash flow into higher-value activities such as core process R&D and front-end wafer fabrication (e.g., 12-inch, SiC). This restructure not only improves capital efficiency but enhances operational agility in response to market fluctuations. Over the long term, this model enables IDM firms to balance "capital-light" with "stable profitability" while maintaining technology leadership and supply-chain resilience.

2.2.3 Infineon: SiC Packaging Collaboration to Enhance Mid-Term Supply-Chain Resilience

In September 2025, Infineon Technologies and ROHM Semiconductor announced a memorandum of understanding (MoU) to establish a cooperative framework for silicon-carbide (SiC) power-device packaging. The agreement covers technology sharing for specific top-side cooling packages, with both parties serving as secondary suppliers to each other. In the mid-term, this collaboration will materially strengthen the resilience of the SiC power-device supply chain. High-end customers in automotive, industrial, and AI data-center applications will benefit from access to package-compatible products from two leading technology providers, mitigating single-supplier risks and streamlining design verification processes. Long term, standardization of packaging and supplier diversification is expected to accelerate SiC adoption across renewable energy, electric vehicles, and other high-growth markets, while establishing a foundation for deeper cooperation in broader power-semiconductor technologies.

2.2.4 Microchip: Industry's First 3 nm PCIe 6.0 Switch Addresses AI Data-Center Interconnect Bottlenecks

In October 2025, Microchip Technology launched the world's first 3 nm Switchtec™ Gen 6 PCIe® switch. In the short term, this product provides critical interconnect solutions for next-generation AI server deployments, alleviating bandwidth constraints between GPUs and CPUs caused by exponential data growth. Mid-term, it doubles per-lane bandwidth from PCIe 5.0's 32 GT/s to 64 GT/s, supporting up to 160 lanes. The combination of doubled bandwidth and high port density is pivotal for scaling AI clusters and accommodating rapid increases in compute units, minimizing processor idle cycles and enhancing overall system efficiency. Long term, integrated post-quantum cryptography and other security features address evolving hardware-level security requirements for future data centers, establishing significant technological barriers and competitive advantages for Microchip in the AI infrastructure ecosystem.

2.2.5 SK Hynix: Launch of “AIN Family” AI-Oriented Storage Solutions

In October 2025, SK Hynix officially introduced its “AIN Family” high-performance NAND storage lineup at OCP 2025, encompassing high-bandwidth (B), high-density (D), and high-performance (P) modules specifically engineered for AI inference and training workloads. In the short term, this strategic move strengthens SK Hynix’s foothold in the AI-specialized storage market, particularly across AI training and edge computing scenarios. Mid-term, it is expected to enhance the adoption of its storage products within cloud data centers, improving both pricing leverage and margin potential. Long term, successful commercialization of advanced NAND technologies (e.g., HBF/stacked architectures) could enable SK Hynix to secure a leadership position in the high-end AI storage segment. Key risks include technology deployment timelines, cost management, and cyclical fluctuations in the storage market.

2.2.6 Cmsemicon: Revenue Growth Amid Profit Pressure, Mid-Term Transformation Challenges

Cmsemicon reported Q3 2025 revenue of CNY 269 million, up 21.88% YoY, reflecting a broad recovery in the semiconductor market; net profit, however, declined 3.66% YoY to CNY 65.82 million. In the short term, revenue growth highlights the company’s benefit from industry recovery and increased market acceptance of its products. Mid-term, margin compression reflects ongoing business transformation and product iteration, driven by elevated R&D expenditure, higher costs for new product launches, and intensifying competition. The company must carefully balance short-term profitability with sustained investment in growth initiatives to enable a smooth transition from traditional products to higher-value offerings. Long term, successful product portfolio optimization and the development of technical leadership in niche segments could position Cmsemicon for sustainable growth despite current profitability pressures.

2.3 Long-term Implications

2.3.1 Silex: Silex Stake Sale Drives Short-Term Profit, Poses Long-Term Strategic Challenges

Silex's Q3 2025 report, released on October 27, indicates that the company achieved a net profit of CNY 1.576 billion, up 2,199.1% YoY, through the sale of its controlling stake in its Swedish subsidiary. In the short term, this transaction delivered substantial non-recurring gains, materially improving the quarter's financial performance and bolstering cash reserves. From a long-term strategic standpoint, however, the divestment reflects a "sacrificing the vehicle to save the driver" approach: the Swedish subsidiary, as Silex's core MEMS process development and manufacturing platform, represents a critical loss of high-end MEMS capabilities accumulated over years. Furthermore, the company's net profit excluding non-recurring items remained negative, widening to CNY -235 million, exposing structural profitability weaknesses in its core operations. Over the long term, the key challenge lies in rebuilding core competitiveness and sustaining growth without this technical support.

2.3.2 CXMT: Proposed 2026 STAR Market IPO, Strategic Valuation Significance

CXMT intends to pursue a 2026 IPO on the STAR Market, targeting a valuation of approximately CNY 300 billion and fundraising between CNY 20–40 billion. A successful listing would provide critical capital for R&D and capacity expansion, advancing China's self-reliance in DRAM and HBM memory technologies. Strategically, the IPO marks a major milestone in the domestic memory substitution pathway, potentially reducing dependency on global suppliers and strengthening China's memory industry competitiveness on the international stage. Key success factors remain technological breakthroughs and rapid market share expansion, as well as execution against mass-production timelines.

2.3.3 ASE: Major Investment in Advanced Packaging to Address Long-Term AI Chip Demand

Global OSAT leader ASE announced in October 2025 a substantial investment to construct the K18B advanced packaging fab in Kaohsiung Science Park, China, focusing on CoWoS and high-end chip packaging capacity, with completion expected in 2028. In the short term, this investment reflects the urgent demand for advanced packaging driven by AI accelerators, positioning ASE as a primary beneficiary. In the mid-term, the new fab will help alleviate global CoWoS and advanced packaging capacity constraints, providing critical supply support across the ecosystem, including TSMC. Over the long term, as Moore's Law slows, Chiplet and heterogeneous integration are emerging as mainstream pathways to enhance chip performance, making advanced packaging technology and capacity as strategically important as front-end process nodes. ASE's large-scale investment represents a strategic move to consolidate its core position in back-end manufacturing and capture sustained growth opportunities from AI and HPC applications.

2.3.4 Yageo: Acquisition of Shibaura Electronics Strengthens Long-Term High-End Component Portfolio

In October 2025, Yageo Corporation announced its plan to acquire Shibaura Electronics for TWD 22.8 billion in full, with the transaction expected to close in Q1 2026. From a long-term strategic perspective, this acquisition is a critical step in Yageo's high-end component strategy, following prior integrations of KEMET and Pulse. By incorporating Shibaura Electronics' key offerings, including temperature and current sensors, Yageo will enhance its high-end product portfolio, forming a more complete solution matrix in fast-growing sectors such as automotive electronics and industrial control. Long term, this acquisition accelerates Yageo's transformation from a traditional passive component supplier into a comprehensive provider of sensors, passive components, and modular solutions, significantly improving its global competitive positioning. With sustained growth in high-end sensor demand from EVs and industrial automation, this M&A establishes a solid foundation for Yageo's long-term sustainable market leadership.

2.3.5 Skyworks & Qorvo: Strategic Merger to Reshape Long-Term RF Chip Market Dynamics

On October 28, 2025, U.S. RF semiconductor leaders Skyworks and Qorvo announced a merger valued at USD 22 billion, expected to close in early 2027. From a long-term strategic standpoint, this merger is designed not as a short-term defensive measure but to reshape the global RF front-end chip market's competitive landscape. The combined entity will integrate complementary technology portfolios and over 12,000 patents, achieving comprehensive coverage across smartphones, defense & aerospace, and automotive electronics. Long term, the merger is projected to create an industry leader with annual revenues of approximately USD 7.7 billion, delivering significant cost synergies (estimated annual savings of USD 500 million) and enhanced R&D capabilities. This consolidation strengthens the company's ability to respond to in-house chip development by major customers and reinforces U.S. supply chain control and global influence in the RF semiconductor segment. Completion remains subject to stringent antitrust review by key global regulatory authorities.

03

Application Updates

3. Application Updates Overview

Category	Section	Manufacturer	Updates
Artificial Intelligence	AI Chip	OpenAI Broadcom	OpenAI and Broadcom Collaborate on Custom AI Chips
Artificial Intelligence	AI Chip	NVIDIA	NVIDIA AI Chip Blackwell (GPU) Now Fully in Production in the U.S.
Artificial Intelligence	Cloud Computing & Big Data	Qualcomm	Qualcomm Unveils Two Data Center-Class AI Inference Chips
Artificial Intelligence	Cloud Computing & Big Data	Intel	Intel Launches Next-Generation Data Center GPU
New Energy	Photovoltaics & Energy Storage	CATL	CATL Advances Development of Sodium-Ion Passenger Vehicle Batteries
New Energy	New Energy Vehicles	BYD	BYD Malaysia Plant Scheduled for 2026 Production
Consumer	Smartphones	HONOR	Honor Launches Flagship Magic8 Series
Consumer	Smartphones	vivo	vivo Unveils X300 Series Flagship Smartphones in Shanghai
Consumer	Robotics	Alibaba Cloud Nvidia	Alibaba Cloud and NVIDIA Announce Physical AI Collaboration, Focusing on Embodied Intelligence and Assisted Driving
Industrial	Industrial Automation & Control	Schneider	Schneider Partners with Hongyu to Launch Okken Authorized Distribution Boards, Advancing Power Infrastructure Modernization
Industrial	Industrial Automation & Control	Rockwell	Rockwell Automation Launches Free FactoryTalk Design Workbench for Micro-Control Systems

Category	Section	Manufacturer	Updates
Automotive	Automotive Supply Chain	Nexperia	Automakers Scramble for Chips Amid Nexperia Supply Constraints
Automotive	Automotive Supply Chain	Nvidia	NVIDIA Unveils Hyperion 10: Integrated Hardware-Software Platform for Autonomous Driving
Telecommunications	Communication Networks & Optical Fiber	ZTE	ZTE Secures Top Position in China's Cloud Terminal Market
Telecommunications	Communication Networks & Optical Fiber	Nvidia	NVIDIA Invests $1 Billion in Nokia to Advance AI-Driven 6G Networks
Medical Equipment & Devices	Medical Imaging Equipment	UNITED IMAGING HEALTHCARE	United Imaging Healthcare Signs INR 25 Billion Radiology Equipment Procurement Agreement with India's Super Health

3.1 Artificial Intelligence

3.1.1 OpenAI and Broadcom Collaborate on Custom AI Chips

On October 13, the AI leader and Broadcom announced that the two companies will jointly develop a 10-gigawatt-scale custom AI chip and network system rack. Following the announcement, Broadcom's stock surged nearly 10% at Monday's open, with market capitalization increasing by over USD 150 billion. OpenAI will lead the chip and system design, while Broadcom will be responsible for joint development and deployment. Deployment is planned to start in the second half of 2026 and is expected to be fully completed by the end of 2029.

3.1.2 NVIDIA AI Chip Blackwell (GPU) Now Fully in Production in the U.S.

On October 18, Jensen Huang stated that NVIDIA's fastest AI chip, the Blackwell GPU, is now fully in production in Arizona. Demand for the GPU remains strong, with 6 million Blackwell GPUs shipped over the past four quarters. The combined revenue of Blackwell and the Rubin chip, set to launch next year, is expected to reach USD 500 billion.

3.1.3 Qualcomm Unveils Two Data Center-Class AI Inference Chips

October 28 – Qualcomm announced two data center-class AI inference chips, the AI200 and AI250, accompanied by full-rack acceleration solutions. The new chips utilize a neural processing unit (NPU) architecture, with each card supporting up to 768GB of low-power memory. They are optimized for AI model inference rather than training and claim to deliver industry-leading performance at a lower total cost. Industry impact: Qualcomm's entry into the data center AI chip market challenges NVIDIA's position, intensifying competition in the AI inference chip segment. Following the announcement, Qualcomm's stock rose over 11% in a single day.Humanize 107 words

3.1.4 Intel Launches Next-Generation Data Center GPU

At the OCP Global Summit on October 14, Intel officially unveiled its next-generation data center GPU, codenamed "Crescent Island." This product is designed to meet the growing AI inference workload demand, featuring Intel's Xe3P microarchitecture and up to 160GB of LPDDR5X memory. The launch marks another key advancement for Intel in the data center GPU market.

3.2 New Energy

3.2.1 CATL Advances Development of Sodium-Ion Passenger Vehicle Batteries

October 26 – At a recent investor relations event, CATL (386.940, 1.17, 0.30%) disclosed potential applications for sodium-ion batteries and updates on its sodium battery products. The company highlighted that sodium batteries offer advantages in low-temperature performance, carbon footprint, and safety, making them suitable for both passenger and commercial vehicle power applications. CATL's newly developed sodium battery has passed the new national standard certification, becoming the world's first sodium-ion battery to achieve this certification. The sodium-ion passenger vehicle power battery is currently under development and deployment with customers, progressing smoothly.

3.2.2 BYD Malaysia Plant Scheduled for 2026 Production

October 13 – During an institutional research session, BYD announced that its assembly plant (CKD) in Malaysia is expected to commence production in 2026. The establishment of the Malaysian plant marks a new chapter in BYD's development in the country. BYD emphasized that its commitment extends beyond delivering innovative products to comprehensive investment in the local electric ecosystem, including local assembly, talent development, and promotion of electric mobility.

3.3 Consumer

3.3.1 Honor Launches Flagship Magic8 Series

October 15 – Honor unveiled a range of full-scenario products, with the flagship Magic8 series as the highlight. This new model is officially defined as a "self-evolving AI-native smartphone" and incorporates multiple innovative solutions from Goodix Technology. Additionally, Honor introduced several other products, including the MagicPad3 Pro, MagicPad3 12.5, Honor Watch 5 Pro, Honor Earbuds 4, and the Honor-selected KUMI AI Note.

3.3.2 vivo Unveils X300 Series Flagship Smartphones in Shanghai

October 13 – vivo launched its X300 series flagship smartphones in Shanghai. The X300 standard model focuses on a compact flagship imaging experience, featuring the world's first MediaTek Dimensity 9500 chip and a 200MP ultra-high-resolution main camera. The X300 Pro model upgrades imaging, stabilization, and performance comprehensively. This series marks vivo's 30th anniversary milestone, introducing multiple innovations in photography algorithms and chip-level custom tuning.

3.3.3 Alibaba Cloud and NVIDIA Announce Physical AI Collaboration, Focusing on Embodied Intelligence and Assisted Driving

Recently, Alibaba Cloud and NVIDIA established a partnership in the field of Physical AI. Alibaba Cloud's AI platform PAI will integrate NVIDIA's Physical AI software stack, providing enterprise users with end-to-end platform services including data preprocessing, synthetic data generation, model training and evaluation, robotic reinforcement learning, and simulation testing. This collaboration aims to shorten development cycles for applications in embodied intelligence and assisted driving. Physical AI is a branch of artificial intelligence extending into the physical world, designed to enable interaction with the real world by integrating multimodal perception, spatial relationship understanding, and physical rule cognition.

3.4 Industrial

3.4.1 Schneider Partners with Hongyu to Launch Okken Authorized Distribution Boards, Advancing Power Infrastructure Modernization

Schneider Electric announced a strategic collaboration with Taiwanese distribution board manufacturer Hongyu Electric to officially introduce the IEC 61439-compliant "Okken Authorized Distribution Board." This partnership delivers three primary advantages: adherence to the highest safety standards, enhanced operation and maintenance efficiency, and optimized operational costs. The initiative exemplifies the integration of global technological expertise with localized manufacturing capabilities, effectively addressing Taiwan's high-tech sector's critical demand for secure and highly reliable power systems.

3.4.2 Rockwell Automation Launches Free FactoryTalk Design Workbench for Micro-Control Systems

On October 28, Rockwell Automation officially released the FactoryTalk Design Workbench, a free software solution for designing micro-control systems. The platform supports Micro800 series programmable controllers and provides a unified environment for programming, configuration, and debugging, streamlining the development of compact standalone automation systems. With an interface consistent with the Rockwell Logix ecosystem, the tool enables rapid onboarding, improves deployment and debugging efficiency, and facilitates simultaneous management of multiple controller devices.

3.5 Automotive

3.5.1 Automakers Scramble for Chips Amid Nexperia Supply Constraints

October 29 — Global automakers are actively seeking semiconductor supplies and confirming inventory availability as a growing supply disruption involving Dutch company Nexperia threatens automotive production worldwide. The disruption follows the Dutch government's takeover of Nexperia and the prohibition of exports from China, driven by concerns that Nexperia's technology could be transferred to its Chinese parent company, Wingtech. The U.S. has designated Wingtech as a potential national security risk.

3.5.2 NVIDIA Unveils Hyperion 10: Integrated Hardware-Software Platform for Autonomous Driving

On October 28, NVIDIA officially launched the Hyperion 10 platform, delivering a fully integrated autonomous driving solution that spans in-vehicle AI chips to large-scale driving models. The platform utilizes dual Thor automotive-grade superchips, providing a combined INT8 compute capacity of approximately 2,000 TOPS, and enables converged processing for both in-cabin entertainment and advanced driving functions.

3.6 Telecommunications

3.6.1 ZTE Secures Top Position in China's Cloud Terminal Market

According to the "2025 H1 China Cloud Terminal Market Tracker Report" released by International Data Corporation (IDC), ZTE captured a 44.5% market share, maintaining its leadership in China's cloud terminal market. For the second consecutive year, ZTE ranked first across overall cloud terminal shipments, VDI solution cloud terminals, and commercial cloud terminal shipments, while continuing to significantly outperform competitors in the consumer cloud terminal segment.

3.6.2 NVIDIA Invests $1 Billion in Nokia to Advance AI-Driven 6G Networks

On October 28, NVIDIA announced a $1 billion strategic investment in Finnish telecom equipment provider Nokia, establishing a partnership to jointly develop AI-enabled 6G network solutions. Nokia will integrate NVIDIA's GPU and AI technologies to build intelligent mobile network infrastructure, including next-generation 5G/6G base stations and wireless access equipment centered on AI capabilities. The announcement drove Nokia's stock price up 20% in a single trading day.

3.7 Medical Equipment & Devices

3.7.1 United Imaging Healthcare Signs INR 25 Billion Radiology Equipment Procurement Agreement with India's Super Health

United Imaging Healthcare (UIH) has secured a procurement agreement exceeding INR 25 billion (≈RMB 2 billion) with the Indian hospital network Super Health. Under the agreement, UIH will supply, install, and provide full lifecycle management for advanced radiology systems across 100 upcoming Super Health hospitals, enabling clinicians to deliver high-quality medical services. As of H1 2025, UIH reported overseas revenue of RMB 1.142 billion, up 22.48% YoY, accounting for 18.99% of total revenue. This landmark collaboration sets a record in India's radiology equipment procurement history and underscores China's high-end medical equipment sector moving from pure product export to strategic global ecosystem co-development.

04

Product Updates

4. Product Updates

4.1 Memory Chips

Storage Chip Market Key Movements (Oct 2025)

Product Category	Model	Price Trend	Lead Time (Weeks)	Supply-Demand Status
DDR4	8GB	Rising	2-3	In Equilibrium
DDR5	16GB	Rising	3-6	Some Constraints
NAND Flash	128GB	Rising	3-6	Some Constraints
eMMC	32GB	Rising	2-3	In Equilibrium
HBM	HBM3E	Rising	6-8	Some Constraints
SSD	120GB	Rising	6-8	In Equilibrium

Source: TrendForce, CFM, Fusion

4.1.1 Spot NAND and DRAM Supplies Tighten Across the Board, Memory Prices Rise Firmly

1) Product Updates

DDR4/DDR5: Sustained robust demand for networking equipment in data centers is extending the lifecycle of legacy memory such as DDR4. Market underestimation of DDR4's critical role in data center switches is likely to further support ASP growth. While DDR5 represents the next-generation standard, the majority of network switches—including NVIDIA Spectrum and NVLink—still predominantly use DDR4.

NAND Flash: Intensified supply chain bottlenecks are constraining production, resulting in a broad-based price increase of 5–10%.

eMMC: Process upgrades at fabs have impacted output, while enterprise SSD demand is crowding out supply. Sellers maintain pricing power, with eMMC showing stronger price growth than UFS.

HBM3E: Price gains are primarily driven by high-end server, AI, and GPU market demand.

SSD: Rising costs and continued supply control are prompting PC vendors to accelerate design-in of QLC NAND–based SSD solutions. Some PC clients have recently issued substantial QLC SSD orders. Despite price increases, suppliers are maintaining strict shipment control. Overall, the SSD market exhibits volume-constrained price growth.

2) Market Trends

Severe DRAM Shortage in the Consumer Market: Since Q2, DDR4 supply from leading fabs has contracted sharply, leaving most application markets with effectively no DDR4 availability. Capacity is being increasingly redirected toward advanced DRAM products, including DDR5 and HBM. Concurrently, the server market—capable of absorbing large volumes and delivering higher margins—has become the primary supply focus. As a result, DRAM supply for the consumer segment remains constrained, creating a pronounced structural shortage.

Broad-Based Storage Price Inflation Across Applications: With fab-level supply interventions, spot market prices for all memory resources, including NAND and DRAM, have accelerated sharply. Rising upstream costs and tightening supply chains have significantly increased production expenses, driving widespread price hikes for storage products across servers, smartphones, PCs, and other applications. Some low-end smartphone models are even implementing capacity reductions to mitigate cost pressures.

Rigorous Shipment Control by Storage Vendors: Storage brands are generally slowing order fulfillment, with market transactions dominated by small-batch orders. Supplier behavior continues to be the key determinant of market dynamics. If resource tightness persists, the supply-demand balance will increasingly favor vendors, reinforcing cautious inventory management and reluctance to oversell, which is expected to sustain the upward trajectory of storage product pricing.

3) Manufacturer Updates

Micron: Announced the release of 192GB SOCAMM2 customer samples to accelerate the adoption of low-power DRAM in AI data centers. SOCAMM2 enhances the functionality of Micron's first LPDRAM SOCAMM, delivering a 50% capacity increase within the same compact form factor. The expanded capacity can reduce time-to-first-token (TTFT) for real-time inference workloads by more than 80%, improving overall system efficiency.

ADATA: Entire product portfolio now facing widespread shortages, with controlled shipments since October. Taiwanese media report that amid an unprecedented supply crunch in the memory industry, ADATA Chairman Chen Li-bai emphasized the uniqueness of the situation. DDR4, DDR5, and NAND Flash product lines are all affected. Despite holding inventory valued at several billion TWD, ADATA has implemented a deliberate allocation strategy to preserve supply.

4.2 GPU

GPU Market Key Movements (Oct 2025)

Product	Model	Manufacturer	Price Trend	Lead Time (Weeks)	Supply-Demand Status
Consumer	GeForce RTX 5090	NVIDIA	Rising	3-16	Some Constraints
Consumer	GeForce RTX 4090	NVIDIA	Rising	3-5	Some Constraints
Consumer	Radeon RX 7900 XTX	AMD	Falling	2-3	In Equilibrium
Data Center	A100 Tensor Core	NVIDIA	Rising	4-6	Some Constraints
Data Center	H100 Tensor Core	NVIDIA	Rising	6-8	Some Constraints
Data Center	32-Bit MCU	AMD	Rising	3-4	Some Constraints

Sources: FUSION, STCN, Digi-Key, statementdog

4.2.1 AI Demand Drives High-End GPU Shortages and Further Price Increases

1) Market Updates

Deepened Partnerships Among Leading Vendors: To address surging market demand, GPU manufacturers—including NVIDIA, AMD, and Intel—are accelerating collaboration with foundries such as TSMC and Samsung to expand capacity at the 7nm and sub-7nm process nodes. NVIDIA and AMD, in particular, are strengthening their partnerships with these foundries and plan to increase production capacity by approximately 10–15% in the second half of 2025.

Shortages of Raw Materials and Critical Components: Supply constraints in high-performance memory—especially GDDR7 and HBM3—are intensifying, leading to production delays for GPUs. The manufacturing of these advanced memory chips requires extremely complex processes and remains capacity-limited, creating supply bottlenecks for flagship products such as NVIDIA's H100 and AMD's Instinct series. Due to the memory shortage, prices for GDDR7 and HBM3 have risen by 5–8%, further driving up overall GPU pricing.

2) Market Trends

Data Center demand remains elevated: NVIDIA's next-generation architecture (e.g., the Blackwell series) has begun shipping, which may influence the supply–demand balance and pricing of previous-generation products such as the H100 and A100. Meanwhile, demand for high-end data center GPUs continues to rise.

Persistent supply challenges: Intel disclosed during its earnings call that its 10/7nm mature-node capacity remains constrained, a situation that may extend into 2026. This indirectly reflects the industry-wide surge in demand for compute accelerators—including GPUs and related components—while supply-side pressure remains significant.

Shifts in competitive dynamics: The move from pure competition to selective collaboration between NVIDIA and Intel highlights the increasing complexity of the AI ecosystem. At the same time, AMD's recent wins of government-level contracts underscore its strengthened position in high-performance computing, demonstrating its capability to compete head-to-head with NVIDIA in the top-tier market.

4.3 CPU

CPU Market Key Movements (Oct 2025)

Product	Model	Manufacturer	Price Trend	Supply-Demand Status
Consumer	i5-14400/F	Intel	Rising	In Equilibrium
Consumer	i5-14600KF	Intel	Rising	In Equilibrium
Consumer	i7-14700K/KF	Intel	Rising	Some Constraints
Consumer	Ultra 7 265K/KF	Intel	Falling	In Equilibrium
Server	Xeon Platinum 8480+ (56 cores)	Intel	Rising	Some Constraints
Server	Xeon Silver 4410 (20 cores)	AMD	Falling	In Equilibrium

Source : ZOL, PConline, SMYigou, Expreview, eBay

4.3.1 AI Becomes the Dominant Driver, Powering Demand Across the Entire Value Chain

A. Consumer

Legacy Intel CPUs See Sharp Increases in Both Price and Volume: Mid-range 12th–14th Gen Core processors (such as the Core i5 series) remain the primary drivers of price hikes. This trend is fueled by strong market demand combined with constrained capacity at Intel's mature Intel 7/10 nodes. Meanwhile, the new Core Ultra 200 series has seen weaker market uptake due to underwhelming performance gains and higher pricing, further sustaining demand for previous-generation models.

AMD Consumer CPUs Remain Relatively Stable: In October, AMD's AM5-socket processors largely maintained stable pricing, with some models even experiencing slight declines. Loose-pack CPUs and pulls offer steeper discounts.

B. Servers

Intel Server CPU Supply Remains Tight: The core imbalance stems from surging demand from data centers and AI workloads. Intel is prioritizing its limited capacity toward the higher-margin server segment. In addition, shortages of substrates and other supporting components continue to exacerbate supply pressures.

2) Market Trends

Demand: The AI PC ecosystem is rapidly taking shape, with both Intel and AMD aggressively promoting their next-generation CPUs featuring integrated NPUs (Neural Processing Units), such as the Core Ultra series. Although current market acceptance varies, this trend signals that localized AI compute (edge computing) is becoming the next key battleground, indicating that future consumer hardware will be increasingly optimized for AI workloads.

Supply: Intel's Intel 7 and Intel 10 nm mature nodes—used to manufacture most Xeon processors and the 13th/14th-generation Core CPUs—are operating at full capacity and facing production bottlenecks. To prioritize higher-margin data-center products, Intel has shifted capacity allocation toward server CPUs. This supply–demand imbalance is expected to persist through Q1 2026.

"AI-Ready" Becomes a Baseline Requirement: Data-center operators are urgently upgrading their infrastructure to efficiently run large language models and other AI workloads. This surge not only drives massive demand for dedicated AI GPUs such as NVIDIA's H100 and Blackwell series, but also boosts demand for high-performance server CPUs (e.g., Intel Xeon, AMD EPYC), which are essential for orchestrating and feeding data to AI GPUs.

Redefining "Mature Nodes": The capacity constraints affecting Intel 7 and Intel 10 nm nodes—which support mainstream products such as the 12th–14th generation Core processors and certain Xeon CPUs—demonstrate that while cutting-edge process technologies matter, capacity allocation for high-volume "mature" or "mainstream" nodes is equally critical to sustaining market demand.

References

[1]Analog Devices, Inc. “ADI Signs Agreement with ASE to Divest Penang Test & Assembly Facility.” Analog.com Press Release, October 2025.

[2]ASE Group. “ASE Begins Construction of K18B Advanced Packaging Facility in Kaohsiung.” ASEGlobal.com Press Release, October 2025.

[3]Broadcom Inc. “Broadcom Introduces Thor Ultra Chip to Accelerate AI Data Center Connectivity.” Broadcom Newsroom, October 2025.

[4]Business Insider. “How Nvidia could end up worth $6 trillion after reclaiming its spot as ...” 2025.

[5]European Commission. "Recommendation on outbound investments (2025/63)," 2025.

[6]Government of the Netherlands. "Statement on Intervention in Nexperia Citing the Goods Availability Act," October 12, 2025.

[7]GigaDevice. "Third Quarter 2025 Financial Report." October 2025.

[8]Infineon Technologies AG. “Infineon and ROHM Announce SiC Packaging Collaboration to Strengthen Supply Chain Resilience.” Infineon.com Newsroom, September 2025.

[9]Japanese Government. "Cabinet Decision on the Revision of the Information Processing Promotion Act and the Special Account Act," 2025.

[10]Micron Technology, Inc. “Micron Reports Record Fourth Quarter Fiscal 2025 Results.” Investors.Micron.com, September 2025.

[11]Microchip Technology Inc. “Microchip Launches Industry’s First 3nm Switchtec™ Gen 6 PCIe® Switch.” Microchip.com Newsroom, October 2025.

[12]Ministry of Commerce of the People's Republic of China (MOFCOM). "Announcements No. 61 and 62 on Expanding the Export Control of Rare Earths and Related Technologies," October 9, 2025.

[13]Ministry of Trade, Industry and Energy (MOTIE), South Korea. "Semiconductor Industry Support Measures in Response to Potential U.S. Tariffs," 2025.

[14]Micron Technology. "Fourth Quarter FY2025 Financial Results." September 2025.

[15]NVIDIA Corporation. “NVIDIA and Deutsche Telekom to Build €1 Billion AI Data Center in Munich.” Newsroom.NVIDIA.com, October 2025.

References

[16]National Development and Reform Commission (NDRC) and Ministry of Finance of China. "Notice on the Formulation of the 2025 List of Integrated Circuit Enterprises or Projects, Software Enterprises Eligible for Preferential Tax Policies (Fagai Gaoji [2025] No. 385)," 2025.

[17]NXP Semiconductors N.V. “NXP Reports Third Quarter 2025 Results.” NXP Official Investor Relations, October 2025.

[18]NVIDIA Corporation. “NVIDIA and Deutsche Telekom to Build €1 Billion AI Data Center in Munich.” NVIDIA Newsroom, October 2025.

[19]Reuters. “China’s ChangXin Memory Technologies Plans $42 Billion IPO on Shanghai STAR Market in 2026.” Reuters Technology News, October 2025.

[20]Reuters. “Nvidia storms past $5 trillion valuation as AI boom powers meteoric rise.” 29 Oct 2025.

[21]S&P Global & J.P. Morgan. "Global Manufacturing PMI," September 2025.

[22]SEMI. "SEMI Urges EU to Quadruple Chip Act Budget, Drives Signature of Semicon Declaration," September 29, 2025.

[23]Semiconductor Industry Association (SIA). "Global Semiconductor Sales Increase 21.7% Year-to-Year in August," October 3, 2025.

[24]SK hynix Inc. “SK hynix Unveils AIN Family High-Performance NAND Storage Solutions at OCP Global Summit 2025.” SKHynix.com Press Release, October 2025.

[25]STMicroelectronics. “STMicroelectronics Reports Third Quarter 2025 Financial Results.” ST.com Investor Relations, October 23, 2025.

[26]Skyworks Solutions / Qorvo Inc. “Skyworks and Qorvo to Combine to Create $22 Billion U.S.-Based Leader in High-Performance RF, Analog and Mixed-Signal Solutions.” SkyworksIR.com / Qorvo.com, October 28 2025.

[27]Samsung Electronics. "Third Quarter 2025 Earnings Report." October 2025.

[28]The Government of the Republic of Korea. "Fiscal Investment Plan for Global Semiconductor Competitiveness Enhancement," April 15, 2025.

[29]TrendForce. “Samsung and SK hynix Plan Q4 DRAM and NAND Price Hikes amid Tight Supply.” TrendForce Report, October 2025.

[30]U.K. Government. "Announcement on Sanctions Against 11 Chinese Entities," October 15, 2025.

References

[31]U.S. Congress. "Chip Security Act (Proposed)," 2025.

[32]U.S. Department of Commerce, Bureau of Industry and Security (BIS). "Department of Commerce Announces Recission of Biden-Era Artificial Intelligence Diffusion Rule, Strengthens Chip-Related Export Controls," 2025.

[33]Wall Street Journal. "U.S. Weighs Requiring 1-to-1 Ratio for Domestic Chip Production vs. Imports," September 2025.

[34]World Semiconductor Trade Statistics (WSTS). "Global Semiconductor Sales Data," 2025.

[35]Yageo Corporation. “Yageo Announces Acquisition of Shibaura Electronics for NT$22.8 Billion.” Yageo.com Investor Relations, October 2025.

[36]赛微电子股份有限公司. “三季度净利润同比激增2199% 核心系瑞典 Silex 控股权出售.” Sina Finance, 27 Oct 2025.

[37]全球半导体观察，“英特尔推出新一代数据中心GPU“Crescent Island”， 2025.10.15

[38]证券时报网，“OpenAI与博通联手开发定制AI芯片，博通股价飙升近10%”，2025.10.14

[39]新浪财经，“比亚迪：马来西亚工厂将于2026年投产”，2025.10.13

[40]新浪财经，“宁德时代：公司钠新乘用车动力电池正在与客户推进开发、落地中”，2025.10.26

[41]国际电子商情，“荣耀旗舰新品Magic8系列采用多款汇顶创新方案”，2025.10.15

[42]CIO Taiwan，“施耐德攜手宏于推 Okken 授權配電盤 驅動電力基礎設施升級”，2025.10.23

[43]汽车之家，“一口价28.99万起 磁浮底盘/新增白色内饰 新款凯迪拉克CT6上市”，2025.10.22

[44]中兴官网，“中兴通讯蝉联中国云终端市场第一”，2025.10.15

[45]动脉网，“20亿，联影医疗签“最大规模”采购合同”，2025.10.23

[46]EET-China，“从100多疯涨到500多！到底谁在买DDR4内存？为啥不买DDR5？”，2025.10.27

[47]CFM闪存市场，“现货NAND、DRAM资源全面供应趋紧，本周存储价格集体强势上涨！”，2025.10.14

[48]CFM闪存市场，“行业SSD价格再度上调但涨幅收敛，整体交易缩量上涨！”，2025.10.21

[49]CFM闪存市场，“威刚：产品线全部面临缺货，进入10月开始惜售”，2025.10.17

[50]CFM闪存市场，“涨价效应持续发酵，行业、渠道SSD及内存条、嵌入式NAND成品再度上调价格”，2025.10.28

[51]CFM闪存市场，“SK海力士：Q3创下季度历史最高业绩，Q4开始供应HBM4，明年正式扩大销售”，2025.10.29

[52]CFM闪存市场，“美光192GB SOCAMM2宣布送样：采用1γ制程技术，能效提升20%”，2025.10.23

[53]证券时报网，“英伟达RTX 4090显卡全网断货，库存几近被扫光，最高涨至5万元”，2025.10.19

[54]阿思达克财经，“英伟达(NVDA.US)称Blackwell晶片已在亚利桑那州全面投产”，2025.10.29

[55]CTIMES，“AMD与美国能源部合作建构新世代超级电脑”，2025.10.28

References

[56]财报狗，“英特爾發表新一代 AI 筆電晶片 "Panther Lake"，首度採用 18A 製程”，2025.10.12

[57]财报狗，“英特爾 10／7 製程供應吃緊　短期無擴產計劃”，2025.10.28

[58]财报狗，“超微、甲骨文深化 AI 合作　將打造全球首個搭載 MI450 GPU 公有雲超級運算叢集”，2025.10.22

[59]中关村在线，“酷睿13/14代处理器价格普涨，日本市场涨幅达10%-20%”，2025.10.12

[60]太平洋电脑网，“英特尔上调海外旧款酷睿i3/i5/i7/i9处理器价格，最高涨幅达15%”，2025.10.17

[61]腾讯网，“【2025年10月】10月装机走向与推荐（市场分析部分/总第114期）”，2025.10.01

[62]深铭易购，“英特尔多代处理器全球提价，部分涨20%”，2025.10.17

[63]超能网，“Intel 10/7节点芯片需求旺盛导致产能吃紧，英特尔将把产能倾向服务器市场”，2025.10.25

[64]EEPW，“需求超过供应 英特尔预警Intel10 和Intel7节点CPU短缺”，2025.10.28

[65]Reportify，“通富微电-2025 年三季度因客户需求强劲超预期”，2025.10.28

[66]曙后星孤网，“怪不得CPU疯狂涨价！Intel CFO：需求异常强劲已供应紧张”，2025.10.30

[67]Reuters，“Automakers hunt high and low for chips as supply crisis worsens”2025.10.30

[68]华尔街见闻，“英伟达超进化！软硬件一把抓，智能驾驶大变局”，2025.10.28

[69]英飞凌官网，“Silicon carbide power modules in new EasyPACK™ C package enhance efficiency and lifetime of industrial applications”，2025.10.29

[70]vivo官网，“巨出片 出巨片，vivo X300系列发布，售价4399元起”，2025.10.13

[71]电子工程专辑，“高通发布AI芯片AI200和AI250，正式进军数据中心市场挑战英伟达”，2025.10.28

[72]Reuters，“Nvidia deal casts AI haze over Nokia valuation ”，2025.10.29

Disclaimer

The monthly report issued by Briocean (hereinafter referred to as "Briocean") is compiled by Briocean's Marketing and Branding department based on publicly available data, information, and research reports.

The content of this report, such as information, opinions, and speculations, solely represents the judgments and perspective of Briocean at the time of the report's issuance. The content is intended for reference purposes only, and does not constitute bids, solicitations, offers or invitations to make offers for the mentioned products. It neither forms the basis of any contractual obligation nor recommendation for the buying or selling of any investment instruments or execution of any transactions. Furthermore, it does not provide investment or procurement advice or guidance. Briocean bears no legal responsibility for any direct or indirect consequences or losses arising from the use of the information and content. Readers are urged to exercise caution, independent judgment, and analysis when reviewing this report.

Briocean does not guarantee the authenticity, accuracy, completeness, or timeliness of the data referenced in this report, research report or information obtained from third-party sources. Published information, opinions, and data may become inaccurate or obsolete due to changing circumstances or other factors after the publication date. However, Briocean is not obligated to update inaccurate or outdated information, opinions, and data, nor will it notify readers of such changes or updates.

October 2025
Briocean

YOUR PREFERRED SUPPLIER FOR GLOBAL SOURCING

Briocean was established in 2008 as ISO14001, IS09001:2015, AS9120B and ANSI/ESDS20.20-2021 certified leading independent electronic component distributor, with our headquarters in Singapore. Our company specialises in insourcing and supply chain management servic es for the elec tronics manufacturing clients across a broad range of industries.

Our global network of over 10,000 vetted suppliers allows us to respond to the unique needs of our clients, from reducing component shortages to achieving significant cost savings. Our robust supplier management system and two state-of-the-art quality assurance centres in Shenzhen and Hong Kong ensure that we deliver reliable, traceable procurement services.

At Briocean, quality is our cornerstone. Our commitment is to ensure that every component we source is of the highest quality.